

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10540992
<b>Filing Date:</b>	05-Jun-2006
<b>Title of Invention:</b>	Chemical-mechanical-polishing slurry composition, method for planarizing surface of semiconductor device using the same, and method for controlling selection ratio of slurry composition
<b>First Named Inventor/Applicant Name:</b>	Jea Gun Park
<b>Filer:</b>	E. Rico Hernandez/Febes Lazo
<b>Attorney Docket Number:</b>	061063-0316598

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>